



Material Content Data Sheet



Sales Product Name				IAUC120N04S6N013		Issued		30. July 2019	
MA#				MA001797304					
Package				PG-TDSON-8-34		Weight*		112.73 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.077	0.96	0.96	9551	9551	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141		
	non noble metal	iron	7439-89-6	0.053	0.05		469		
wire	non noble metal	copper	7440-50-8	52.842	46.86	46.92	468756	469366	
	noble metal	gold	7440-57-5	0.042	0.04	0.04	373	373	
encapsulation	organic material	carbon black	1333-86-4	0.075	0.07		668		
	plastics	epoxy resin	-	5.947	5.28		52758		
leadfinish	inorganic material	silicondioxide	60676-86-0	31.618	28.05	33.40	280483	333909	
	non noble metal	tin	7440-31-5	1.574	1.40	1.40	13961	13961	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1856	1856	
solder	non noble metal	tin	7440-31-5	0.030	0.03		262		
	noble metal	silver	7440-22-4	0.037	0.03		327		
heat sink clip	non noble metal	lead	7439-92-1	1.410	1.25	1.31	12508	13097	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
clip plating	non noble metal	iron	7439-89-6	0.017	0.01		149		
	non noble metal	copper	7440-50-8	16.828	14.93	14.94	149275	149469	
heatspreader	noble metal	silver	7440-22-4	0.639	0.57	0.57	5668	5668	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
*deviation	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2746	2750	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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